

RoHS

COMPLIANT

MI8422-VB Datasheet N-Channel 30-V (D-S) MOSFET

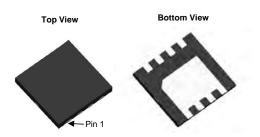
V _{DS}	30	V	
R _{DS(on),typ}	V _{GS} =10V	13	mΩ
RDS(on),typ	VGS=4.5V	19	mΩ
IC	30	А	

FEATURES

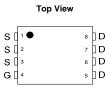
- Halogen-free
- Trench Power MOSFET
- 100 % Rg and UIS Tested

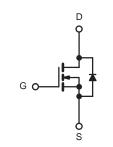
APPLICATIONS

- DC/DC Conversion - Low-Side Switch
- Notebook PC
- Gaming ٠



DFN 3x3 EP





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \text{ °C}$, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		30		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	I _D	20		
	T _A = 25 °C	טי	21.5 ^{b, c}		
	T _A = 70 °C		17.1 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	100	~	
Continuous Source-Drain Diode Current	T _C = 25 °C	l _s	13		
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	3.1 ^{b, c}		
Single Pulse Avalanche Current L = 0.1 mH		I _{AS}	10		
Avalanche Energy	L = 0.1 mm	E _{AS}	5	mJ	
Maximum Power Dissipation	T _C = 25 °C		60		
	T _C = 70 °C	P _D	30	W	
	T _A = 25 °C	טי	3.7 ^{b, c}		
	T _A = 70 °C		2.4 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	27	34	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	6	7.5	0/10	

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static		•		•	•		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 1 mA	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050		27		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- Ι _D = 250 μΑ		- 5.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.0		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	<u> </u>	
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30			А	
	P	V _{GS} = 10 V, I _D = 15 A		13		mΩ	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 10 A		19			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S	
Dynamic ^b	I.	1	1	<u>1</u>		1	
Input Capacitance	C _{iss}				900	pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz			236		
Reverse Transfer Capacitance	C _{rss}				20		
-		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$			20		
Total Gate Charge	Q_g				9	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$			2.1		
Gate-Drain Charge	Q _{gd}]			0.7		
Gate Resistance	Rg	f = 1 MHz	0.2	1.1	2.2	Ω	
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		16	30		
Turn-Off Delay Time	t _{d(off)}	$\rm I_D \cong 10$ A, $\rm V_{GEN}$ = 4.5 V, $\rm R_g$ = 1 Ω		17	35		
Fall Time	t _f]		7	15		
Turn-On Delay Time	t _{d(on)}			14	30	ns	
Rise Time	t _r	V_{DD} = 15 V, R _L = 1.5 Ω		50	100	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		16	30		
Fall Time	t _f			8	18		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			13	•	
Pulse Diode Forward Current ^a	I _{SM}				100	A	
Body Diode Voltage	V _{SD}	I _S = 3 A			1.2	V	
Body Diode Reverse Recovery Time	t _{rr}				40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}				20	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12.5			
Reverse Recovery Rise Time	t _b	1		7.5		ns	

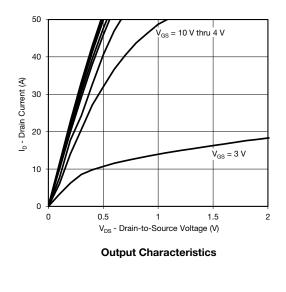
Notes:

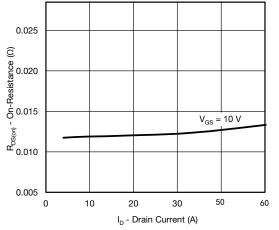
a. Pulse test; pulse width \leq 300 μs , duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

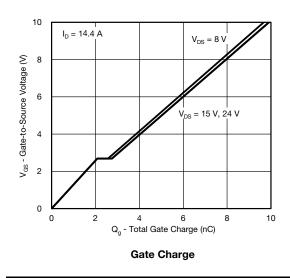


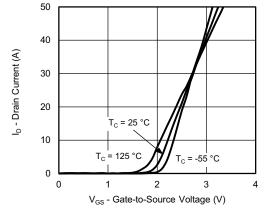
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



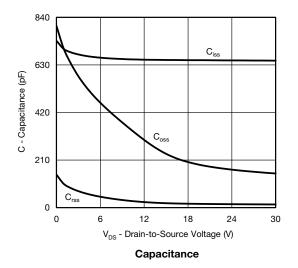


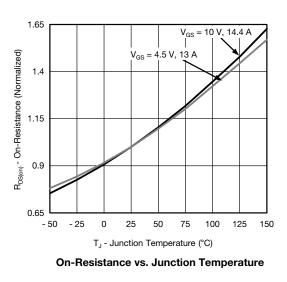
On-Resistance vs. Drain Current





Transfer Characteristics

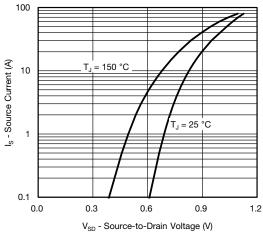




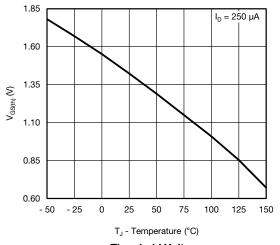
服务热线:400-655-8788



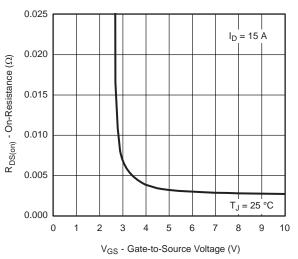
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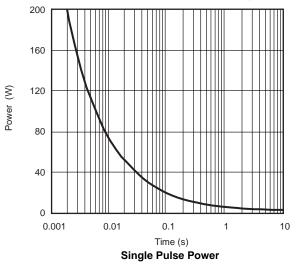
Source-Drain Diode Forward Voltage

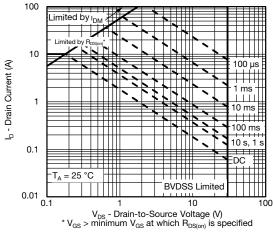


Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage

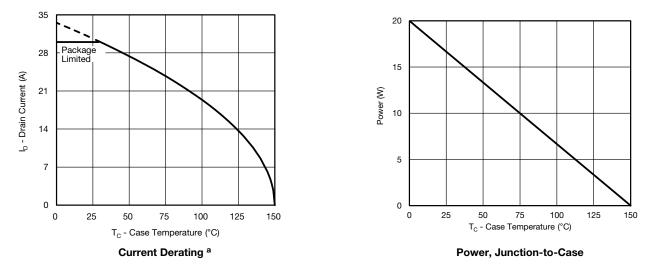




Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

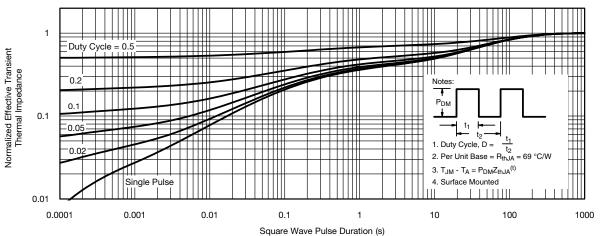


Note

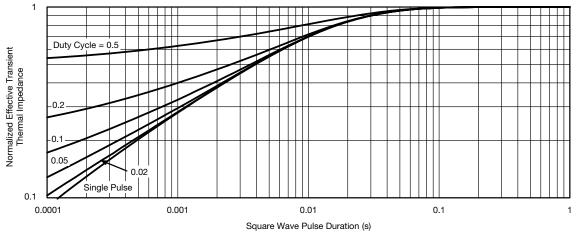
a. The power dissipation P_D is based on T_J max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





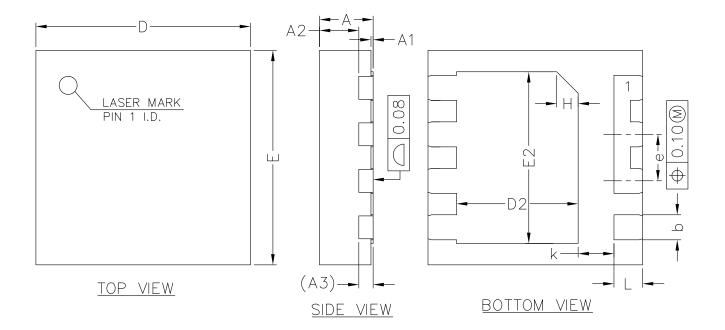


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case







<u>SIDE VIEW</u>

SYMBOL	MIN	NOM	MAX		
А	0.70	0.75	0.80		
A1	0.00	0.02	0.05		
A2	0.50	0.55	0.60		
А3	0.20REF				
b	0.30	0.35	0.40		
D	2.90	3.00	3.10		
E	2.90	3.00	3.10		
D2	1.60	1.70	1.80		
E2	2.30	2.40	2.50		
е	0.55	0.65	0.75		
К	0.40	0.50	0.60		
L	0.35	0.40	0.45		

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)



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